

**In the Abstract:**

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**ABSTRACT OF THE DISCLOSURE**

The circuit device has a contact element, which electrically connects a wave guide (1) with a conductor strip (2) ~~by means of two contacting areas~~. To avoid mechanical stresses due to thermal expansion the contact element is a pre-stressed formed as a precisely prefabricated leaf coil spring having reproducible properties, which is bonded connected at one contacting area of the contacting areas to the wave guide (1) or the conductor strip (2) by means of an electrically conducting adhesive or glue, while a sliding contact is provided on the conductor strip (2) or the wave guide (1) at the other contacting area the second contacting area is provided as a sliding contact, whereby the coil spring is pre- stressed. The prefabricated leaf spring is preferably a MiGA leaf spring precisely made by UV depth lithography and multilayer galvanic methods in a batch production process.